

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"6818608"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 23:32
S2	30	silicon\$1.clm. and resin.clm. and silane.clm. and hydride.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 13:54
S3	0	S2 and calatyt\$3.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 13:27
S4	1	S2 and polymeriz\$4.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 13:27
S5	171487	\$5silane\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 13:55
S6	71181	S5 and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 13:56
S7	4487	S6 and hydride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 13:56
S8	1785	S7 and \$4siloxane\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 13:57
S9	1525	S8 and cataly\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 13:57

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S10	1171	S9 and polymeriz\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 13:57
S11	185	S10 and ((spin adj on) or (spin adj coat\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 14:07
S12	47	S11 and ((wafer adj2 carrier) or (wafer adj substrate) or package\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 14:57
S13	3	(("6406990") or ("6664645")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 18:45
S14	0	257/777,778.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 18:45
S15	4429	257/777,778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 18:45
S16	173	S15 and resin and bump and ultrasonic and wiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 18:46
S17	3552	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 18:48
S18	795	S17 and resin and board	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 18:49
S19	63	S18 and (ultrasonic and resin.clm.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 18:51

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S20	44650	wiring and board and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 18:51
S21	831	S20 and (ultrasonic\$3 near3 wave\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 18:52
S22	334	S21 and bump\$1 and ((wave or ultrasonic\$3) same (resin or bump\$1 or electrode\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 18:53
S23	2	("6406990").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 23:32
S24	453514	(wiring adj board) or (PC adj board) or (circuit adj board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:13
S25	6008	S24 and (resin same melt\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:14
S26	235	S25 and (ultrasonic\$3 same wave\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:15
S27	106	S26 and bump\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:16
S28	94	S27 and electrode\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:16
S29	18	S28 and cool\$3 and solidif\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:17

## EAST Search History

S30	2935	438/108,613.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:25
S31	3130	257/E23.021,E23.121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:26
S32	5574	S30 or S31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:26
S33	2592	S32 and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:26
S34	372	S33 and ultrasonic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:27
S35	88	S27 not S29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 11:27
S36	129	S26 not S27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 13:25
S37	5315	resin.clm. and electrode.clm.	US-PGPUB	OR	OFF	2007/05/19 12:34
S38	121	S37 and ultrasonic.clm.	US-PGPUB	OR	OFF	2007/05/19 12:36
S39	23	S38 and bump.clm.	US-PGPUB	OR	OFF	2007/05/19 12:38
S40	964	S37 and chip.clm.	US-PGPUB	OR	OFF	2007/05/19 12:38
S41	38	S40 and wave.clm.	US-PGPUB	OR	OFF	2007/05/19 12:39
S42	3783	438/106.CCLS.	US-PGPUB; USPAT; JPO	OR	OFF	2007/05/19 13:27
S43	322	S42 AND ULTRASONIC	US-PGPUB; USPAT; JPO	OR	OFF	2007/05/19 13:28

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S44	1264	S42 and bump\$1	US-PGPUB; USPAT; JPO	OR	OFF	2007/05/19 13:28
S45	1145	S44 and bond\$3	US-PGPUB; USPAT; JPO	OR	OFF	2007/05/19 13:28
S46	674	S45 and resin	US-PGPUB; USPAT; JPO	OR	OFF	2007/05/19 13:32
S47	2	("6406990").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/05/19 13:32